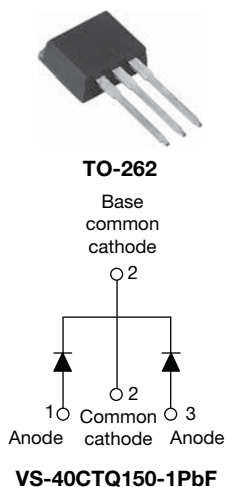
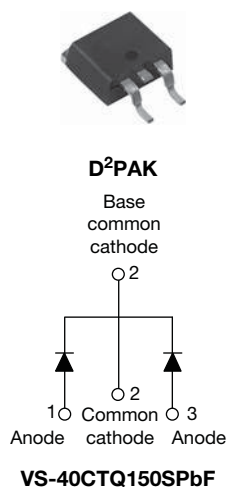


Schottky Rectifier, 2 x 20 A



FEATURES

- AEC-Q101 qualified
- Very low forward voltage drop
- Halogen-free according to IEC 61249-2-21 definition
- 175 °C T_J operation
- Center tap TO-220 package
- High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY

Package	TO-262AA, TO-263AB (D ² PAK)
I _{F(AV)}	2 x 20 A
V _R	150 V
V _F at I _F	0.71 V
I _{RM}	15 mA at 125 °C
T _J max.	175 °C
Diode variation	Common cathode
E _{AS}	1 mJ

DESCRIPTION

The VS-40CTQ... center tap Schottky rectifier has been optimized for very low forward voltage drop, with moderate leakage. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
I _{F(AV)}	Rectangular waveform	40	A
V _R		150	V
I _{FSM}	t _p = 5 μs sine	1500	A
V _F	20 Apk, T _J = 125 °C (per leg)	0.71	V
T _J		- 55 to 175	°C

VOLTAGE RATINGS

PARAMETER	SYMBOL	VS-40CTQ150SPbF VS-40CTQ150-1PbF	UNITS
Maximum DC reverse voltage	V _R	150	V
Maximum working peak reverse voltage	V _{RWM}		

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current See fig. 5	$I_{F(AV)}$	50 % duty cycle at $T_C = 140\text{ }^{\circ}\text{C}$, rectangular waveform	20	A
			40	
Maximum peak one cycle non-repetitive surge current per leg See fig. 7	I_{FSM}	5 μs sine or 3 μs rect. pulse	1500	
		10 ms sine or 6 ms rect. pulse	250	
Non-repetitive avalanche energy per leg	E_{AS}	$T_J = 25\text{ }^{\circ}\text{C}$, $I_{AS} = 1.5\text{ A}$, $L = 0.9\text{ mH}$	1.0	mJ
Repetitive avalanche current per leg	I_{AR}	Current decaying linearly to zero in 1 μs Frequency limited by T_J maximum $V_A = 1.5 \times V_R$ typical	1.5	A

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop per leg See fig. 1	$V_{FM}^{(1)}$	20 A	0.93	V
		40 A	1.16	
		20 A	0.71	
		40 A	0.85	
Maximum reverse leakage current per leg See fig. 2	$I_{RM}^{(1)}$	$T_J = 25\text{ }^{\circ}\text{C}$	50	μA
		$T_J = 125\text{ }^{\circ}\text{C}$	15	mA
Maximum junction capacitance per leg	C_T	$V_R = 5\text{ V}_{DC}$ (test signal range 100 kHz to 1 MHz), $25\text{ }^{\circ}\text{C}$	450	pF
Typical series inductance per leg	L_S	Measured lead to lead 5 mm from package body	8.0	nH
Maximum voltage rate of change	dV/dt	Rated V_R	10 000	V/ μs

Note

(1) Pulse width < 300 μs , duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		- 55 to 175	°C
Maximum thermal resistance, junction to case per leg	R _{thJC}	DC operation See fig. 4	1.5	°C/W
Maximum thermal resistance, junction to case per package		DC operation	0.75	
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased	0.5	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum	Non-lubricated threads	6 (5)	kgf · cm (lbf · in)
	maximum		12 (10)	
Marking device		Case style D ² PAK	40CTQ150S	
		Case style TO-262	40CTQ150-1	

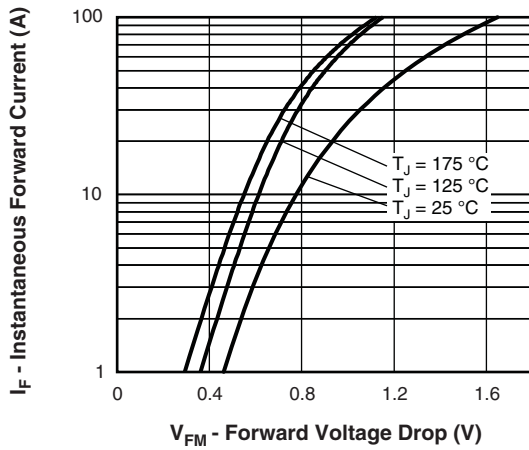


Fig. 1 - Maximum Forward Voltage Drop Characteristics

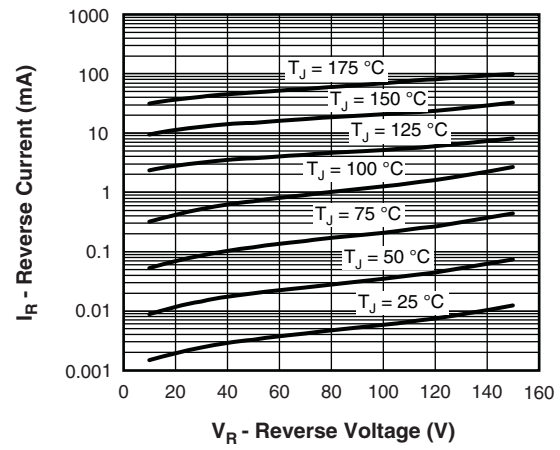


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

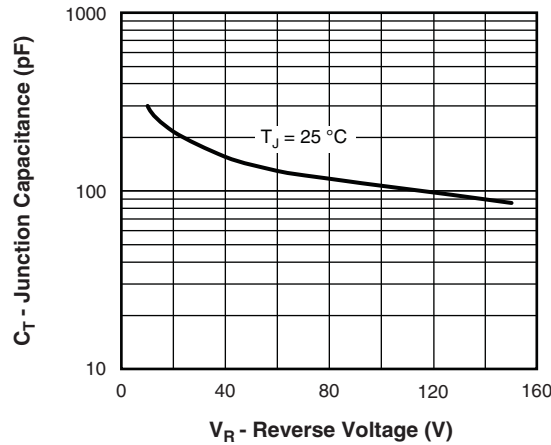


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

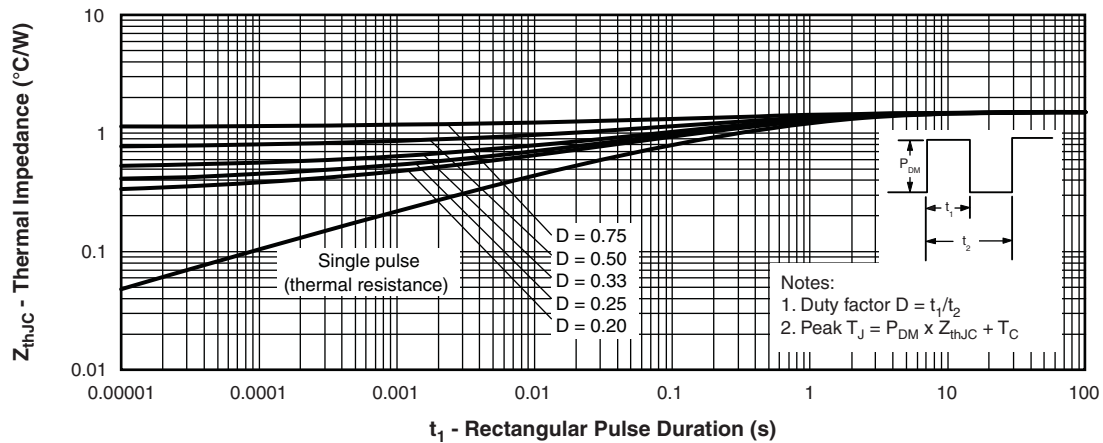


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

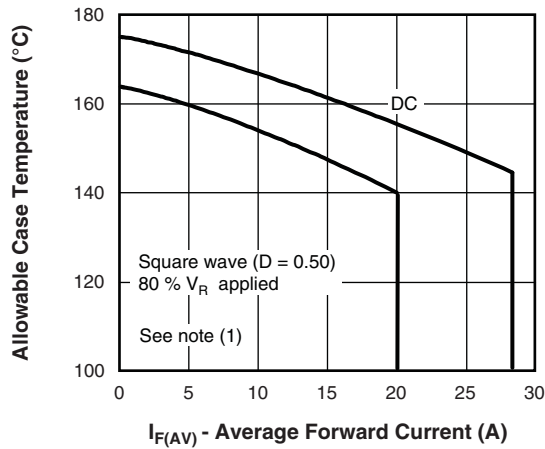


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

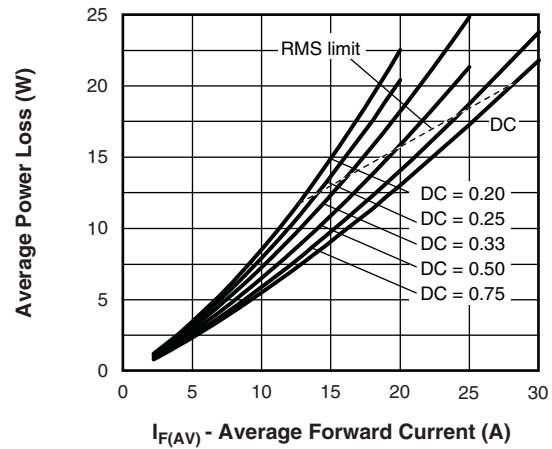


Fig. 6 - Forward Power Loss Characteristics

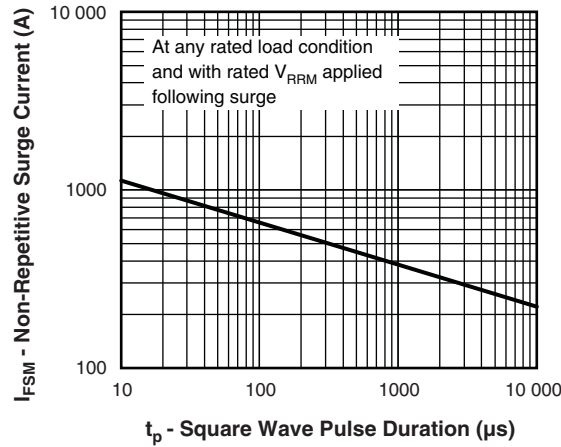


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{d_{REV}}) \times R_{thJC}$;
 P_d = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6);
 $P_{d_{REV}}$ = Inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at $V_{R1} = 80\% V_R$ applied



VS-40CTQ150SPbF, VS-40CTQ150-1PbF

Schottky Rectifier, 2 x 20 A

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code	VS-	40	C	T	Q	150	S	TRL	PbF
	1	2	3	4	5	6	7	8	9
	1	-	Vishay Semiconductors product						
	2	-	Current rating (40 A)						
	3	-	Circuit configuration: C = Common cathode						
	4	-	T = TO-220						
	5	-	Schottky "Q" series						
	6	-	Voltage rating (150 = 150 V)						
	7	-	• S = D ² PAK • -1 = TO-262						
	8	-	• None = Tube (50 pieces) • TRL = Tape and reel (left oriented - for D ² PAK only) • TRR = Tape and reel (right oriented - for D ² PAK only)						
	9	-	PbF = Lead (Pb)-free						

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95014
Part marking information	www.vishay.com/doc?95008
Packaging information	www.vishay.com/doc?95032
SPICE model	www.vishay.com/doc?95434

D²PAK, TO-262

DIMENSIONS FOR D²PAK in millimeters and inches

Conforms to JEDEC outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch

- (7) Outline conforms to JEDEC outline TO-263AB

DIMENSIONS FOR TO-262 in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	2.03	3.02	0.080	0.119	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
L	13.46	14.10	0.530	0.555	
L1	-	1.65	-	0.065	3
L2	3.56	3.71	0.140	0.146	

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Controlling dimension: inches

- (6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline



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